

# TECHNICAL DATA SHEET

## GTEC Thermal XP Board

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### Description

GTEC Thermal XP Board is for use as a superior drylining board laminate with enhanced thermal insulation and more dense polystyrene

### Appearance

GTEC Thermal XP Board is coloured ivory on the front and has orange polystyrene extruded board foam on the back and has tapers down the long edges of the front.

### Composition

Aerated Calcium sulphate di-hydrate enclosed inside a tough paper with bound edges. Core and papers are bonded with starch. Edge glue is PVA. Various thicknesses of Extruded polystyrene (XPS) are factory bonded to 9.5 mm board using PVA adhesive.

### Compliance Authority

GTEC Standard Board complies with BS EN 520:2004+A1:2009 Type A and the laminate complies with the European standard BS EN 13950: 2005  
The XPS Insulation complies with BS EN 13164

### Physical Properties

*Strength to BS EN 520:*

9.5 mm board

Longitudinal breaking load  $\geq$  400N

Transverse breaking load  $\geq$  160N

### Water vapour resistance

27 mm = 9.07 MNs/g

35 mm = 13.07 MNs/g

46 mm = 18.57 MNs/g (Special order only)

55 mm = 23.07 MNs/g

Fire Resistance and Sound Insulation  $R_w$  depend on the system, call Technical Enquiryline for advice.

### Reaction to fire:

*Board* - Euroclass A2-s1,d0 to BS EN 13501-1

*Laminate* - Euroclass B-s1, d0 to BS EN 13501-1

Class 0 to Building Regulations Part B 2006. Self extinguishing if ignited.

### Moisture Content:

< 2 %

### Mass:

27 mm = 6.7 kg/m<sup>2</sup>

35 mm = 6.9 kg/m<sup>2</sup>

46 mm = 7.2 kg/m<sup>2</sup> (Special order only)

55 mm = 7.4 kg/m<sup>2</sup>

The density of the XPS is 30 kg/m<sup>3</sup>

### Thermal Conductivity, $\lambda_R$ :

XPS Insulation: 0.033 W/mK

Plasterboard: 0.19 W/mK

### Thermal resistance, $R$ :

The thermal resistance is significantly superior compared with EPS laminates

27 mm = 0.58 m<sup>2</sup>K/W

35 mm = 0.81 m<sup>2</sup>K/W

46 mm = 1.16 m<sup>2</sup>K/W (Special order only)

55 mm = 1.41 m<sup>2</sup>K/W

### Nail & screw pull through:

> 200 N

### Impact resistance to BS 5234-2 appendix B

Medium Duty

### Environment & Sustainability

Global Warming Potential (GWP) < 5

Ozone Depleting Potential (ODP) = 0

### Fixing

Use either dabs of GTEC Universal Bonding compound, GTEC Wall Lining Adhesive, GTEC Shallow Wall Channels (MFCS) or the GTEC Dryliner System.

### Jointing Finishing & Painting

GTEC Thermal XP Board can be jointed and finished with GTEC Jointing Systems.

The boards require priming with GTEC Universal Sealer prior to decorating.

### Health & Safety

Please read the Laminates Health and Safety Datasheet available on our website or from Enquiryline.

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*Laminate weight:*

19.30 kg for 2400 mm x 1200 mm x 27 mm board

19.87 kg for 2400 mm x 1200 mm x 35 mm board

20.74 kg for 2400 mm x 1200 mm x 46 mm board

21.31 kg for 2400 mm x 1200 mm x 55 mm board

**GTEC Vapour Board option**

The GTEC Thermal XP Board is available with a vapour check layer of metallised polyester film within the laminate which enhances the vapour resistance of the product.

Mean Water vapour resistance factor:

$\mu$  for GTEC Vapour Board = 900

**Authority**



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BU Technical Manager

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